AMENDMENTS TO THE CLAIMS

The listing of claims will replace all prior versions and listings of claims in the application:

Listing of Claims:

 (Currently Amended) A method of fabricating a tunnel junction of a vertical cavity surface emitting laser (VCSEL) with a tunnel junction, the method comprising:

locating a substrate in an MOCVD chamber;

forming an active region over the substrate, the active region having a plurality of quantum wells;

setting a temperature of the MOCVD chamber between 500 °C and 650 °C; and

growing a tunnel junction including GaAs_(I-x)Sb_x on the substrate <u>over the</u> <u>active region</u> using an MOCVD process in which a source of Ga, a source of Sb, and a source of As are present.

- 2. **(Original)** The method according to claim 1, wherein x has a value corresponding to a ratio of As to Sb.
- 3. (Original) The method according to claim 2, wherein the value of x is 0.5.
- 4. (Original) The method according to claim 2, wherein the value of x is less than 0.5
- 5. **(Currently Amended)** The method according to claim 1, wherein the source of Ga is TMGa or TEGa, and the source of Sb is TMSb TMSh.

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- (Original) The method according to claim 1, wherein the source of As is AsH₃ or TBAs.
- 7. (Original) The method according to claim 1, further including carbon doping the $GaAs_{6:0}Sb_v$ using CCI_4 or CBr_4 .

8. (Currently Amended) A tunnel junction comprising:

a p-doped GaAs_(I-x)Sb_x layer, wherein x is set at a value such that the pdoped GaAs_(I-x)Sb_x layer is substantially lattice matched with an InP based active region and has a strain less than 1.95%; and

an n-doped layer of InP, AllnAs, AllnGaAs, or InGaAsP, wherein the n-doped layer is doped with a concentration greater than 5xl0¹⁹ cm⁻³.

 (Previously Presented) The tunnel junction according to claim 8, wherein the p-doped GaAs_(i-x)Sb_x layer is doped with carbon with a concentration greater than 1x10¹⁹ cm⁻³.

10. (Canceled)

- 11. **(Previously Presented)** The tunnel junction according to claim 8, wherein the $GaAs_{(t-x)}Sb_x$ layer is doped with a concentration greater than $5xI0^{19}$ cm⁻³, and wherein the tunnel junction is less than about 10 nanometers thick.
- 12. **(Previously Presented)** The tunnel junction according to claim 8, wherein the n-doped layer is InP, and wherein x has a value of 0.5.

- (Original) A vertical cavity surface emitting laser, comprising: an active region having a plurality of quantum wells, and.
- a tunnel junction over said active region, wherein said tunnel junction includes a $GaAs_{1:n}Sb_x$ layer.
- 14. (Previously Presented) The vertical cavity surface emitting laser according to claim 13, further including an n-type bottom spacer adjacent the active region, and an n-type bottom DBR adjacent the n-type bottom spacer.
- 15. **(Previously Presented)** The vertical cavity surface emitting laser according to claim 13, further including an n-type top spacer adjacent the tunnel junction and an n-type top DBR adjacent the n-type top spacer.
- 16. **(Previously Presented)** The vertical cavity surface emitting laser according to claim 13, wherein the GaAs_{6-w}Sb_x layer is grown by MOCVD.
- 17. **(Previously Presented)** The vertical cavity surface emitting laser according to claim 13, wherein the GaAs_(I-x)Sb_x layer is doped with carbon with a concentration greater than 5xl0¹⁹ cm⁻³.
- (Previously Presented) The vertical cavity surface emitting laser according to claim 13, wherein said active region includes InGaAsP or AllnGaAs.
- (Previously Presented) The vertical cavity surface emitting laser according to claim 18, wherein said tunnel junction includes an n-type InP layer.
- 20. **(Previously Presented)** The vertical cavity surface emitting laser according to claim 13, wherein x is 0.5.

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21. **(Previously Presented)** The vertical cavity surface emitting laser according to claim 13, wherein the tunnel junction has a thickness of less than about 10 nm.